



# SOT619-26(DD)

plastic thermal enhanced very thin quad flat package; no leads; dimple wettable flank, 48 terminals; 7 mm x 7 mm x 0.85 mm body

15 January 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN48
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	04-01-2019
<b>Manufacturer package code</b>	98ASA01354D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7	-	mm
package width	-	7	-	mm
package height	-	0.85	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	48	-	



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2 Package outline

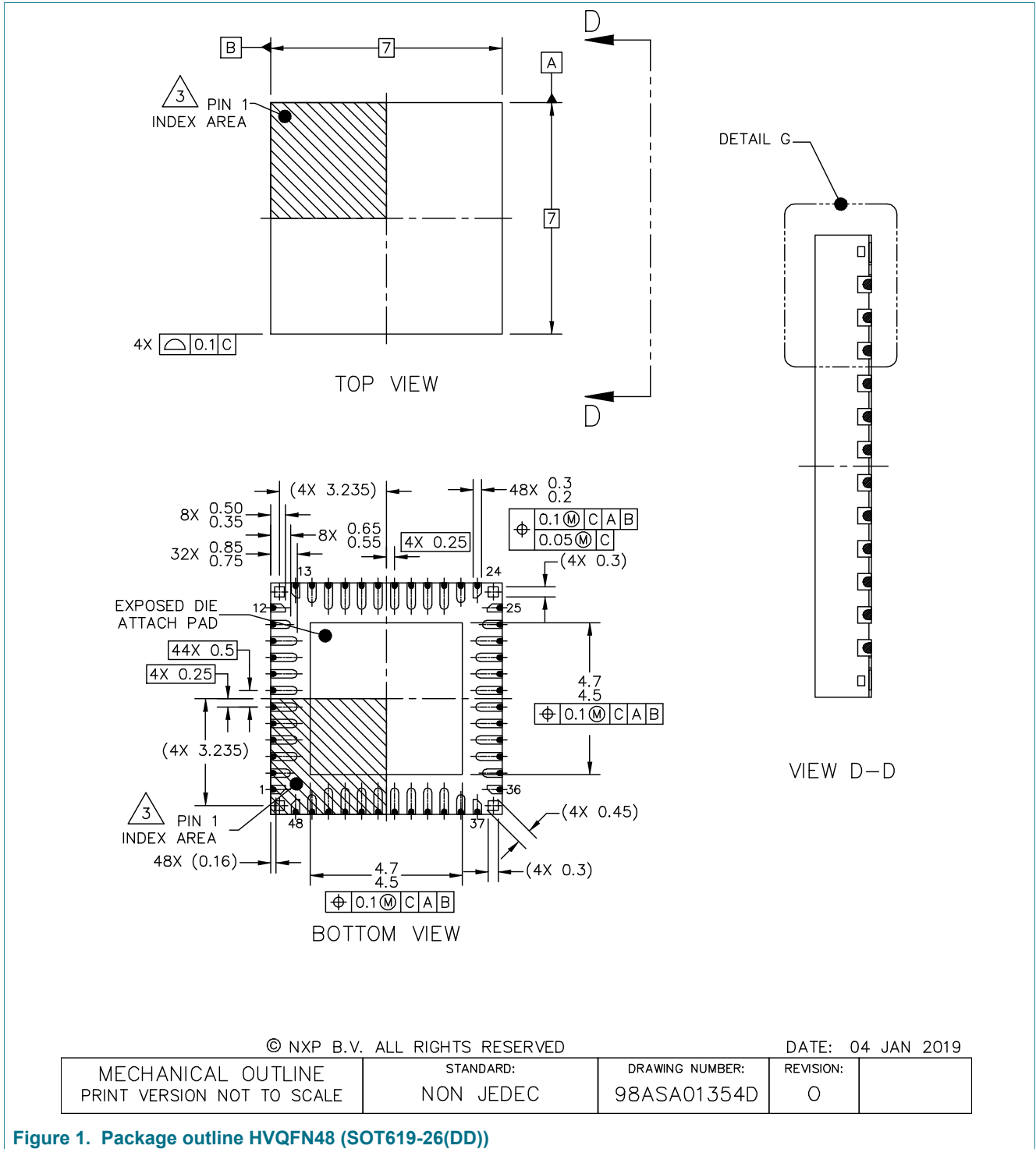


Figure 1. Package outline HVQFN48 (SOT619-26(DD))

plastic thermal enhanced very thin quad flat package; no leads; dimple wettable flank, 48 terminals; 7 mm x 7 mm x 0.85 mm body

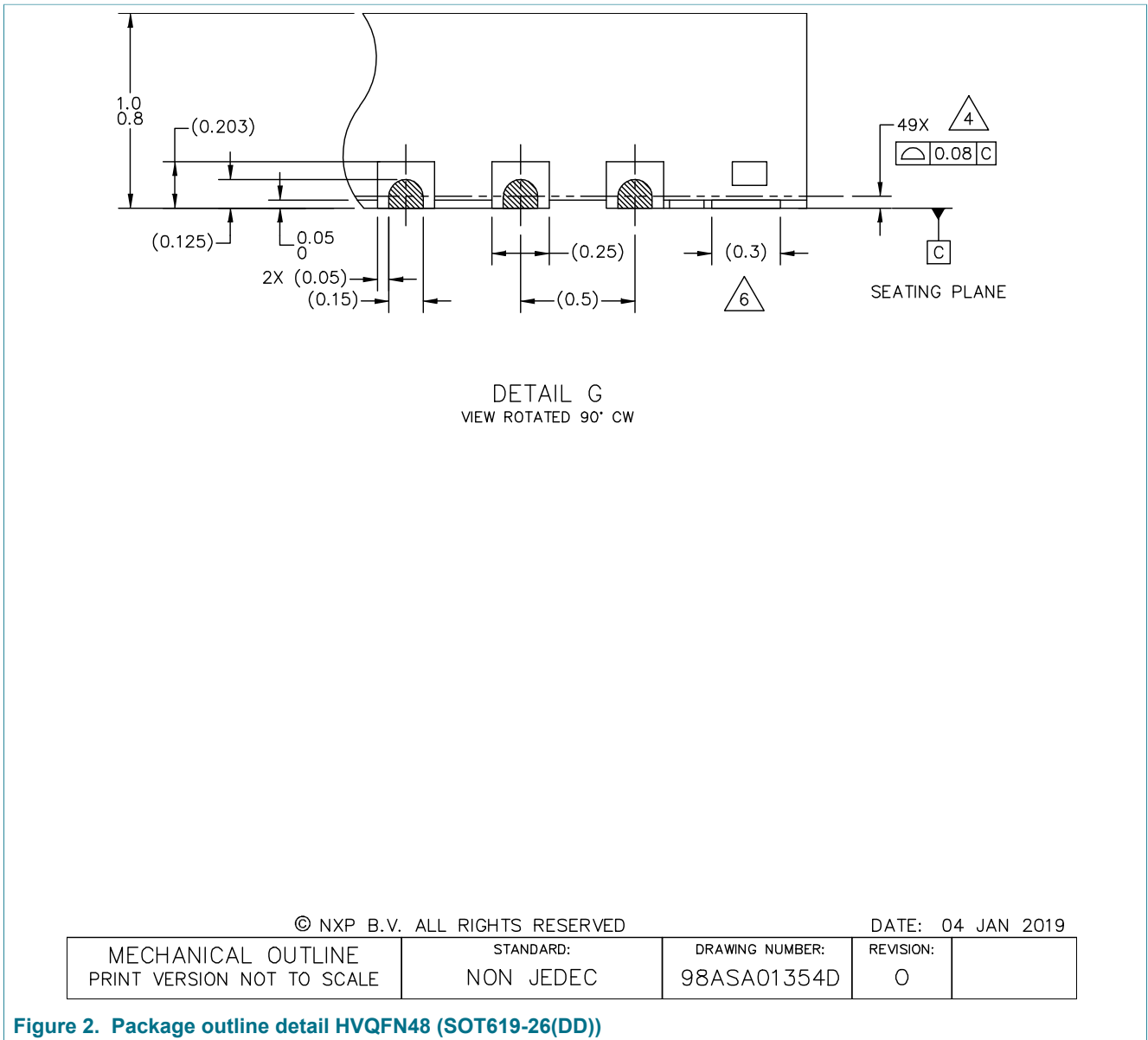


Figure 2. Package outline detail HVQFN48 (SOT619-26(DD))

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3 Soldering

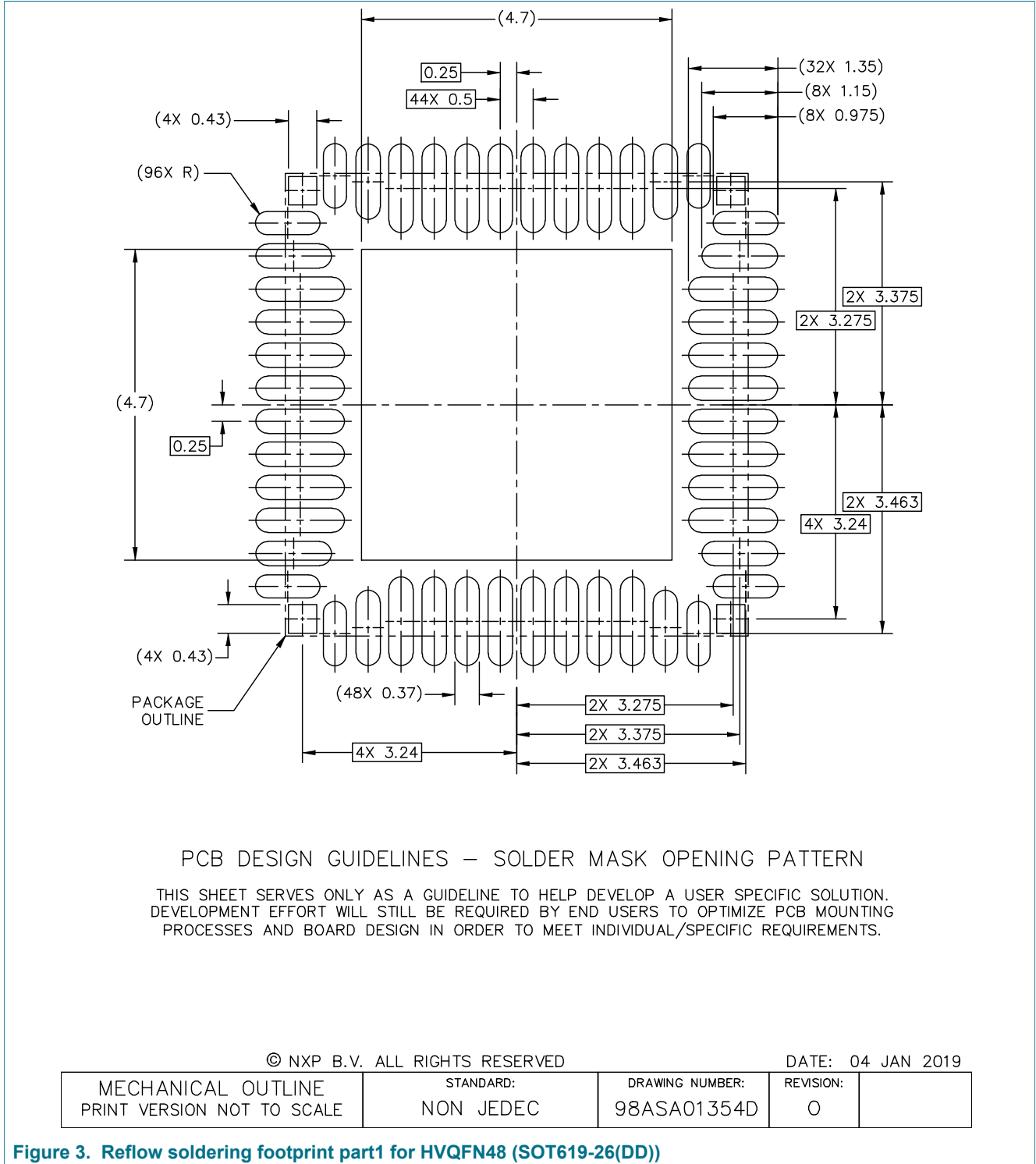
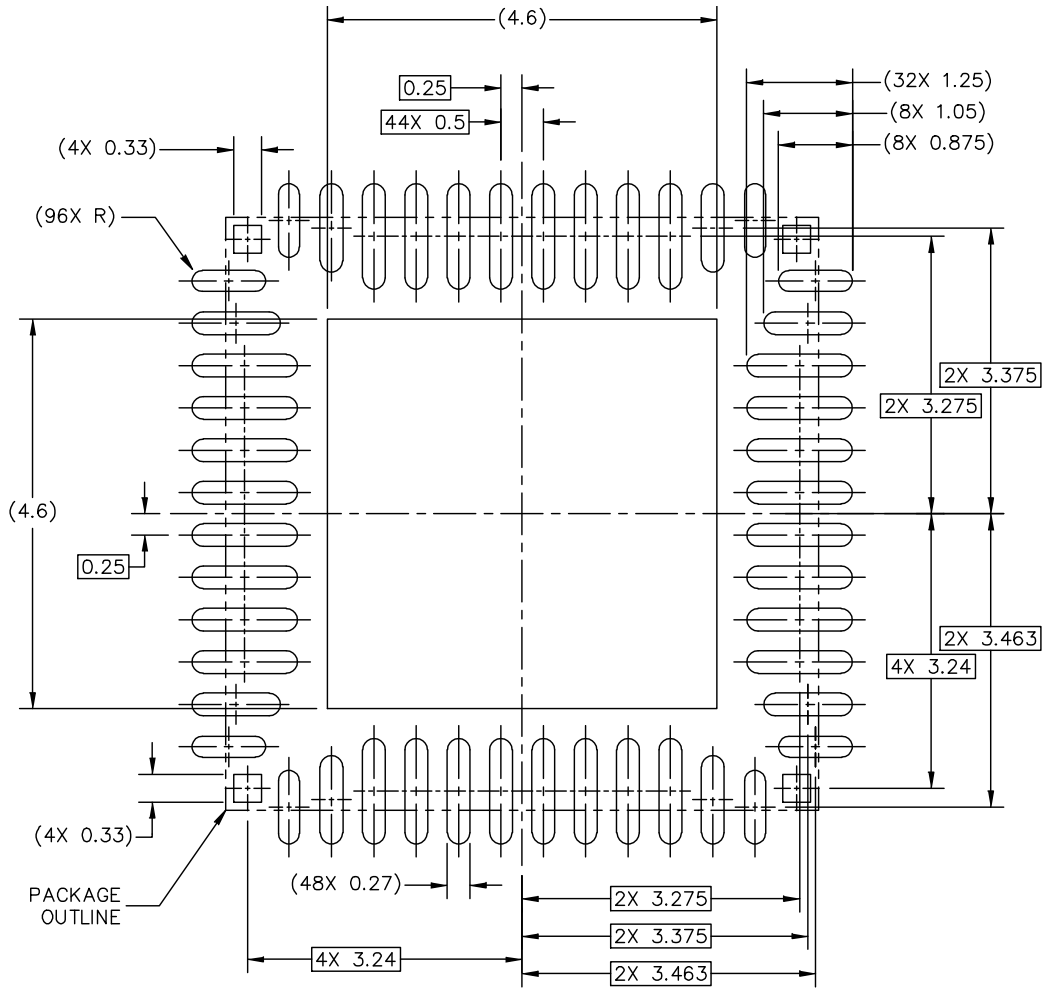


Figure 3. Reflow soldering footprint part1 for HVQFN48 (SOT619-26(DD))

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Figure 4. Reflow soldering footprint part2 for HVQFN48 (SOT619-26(DD))

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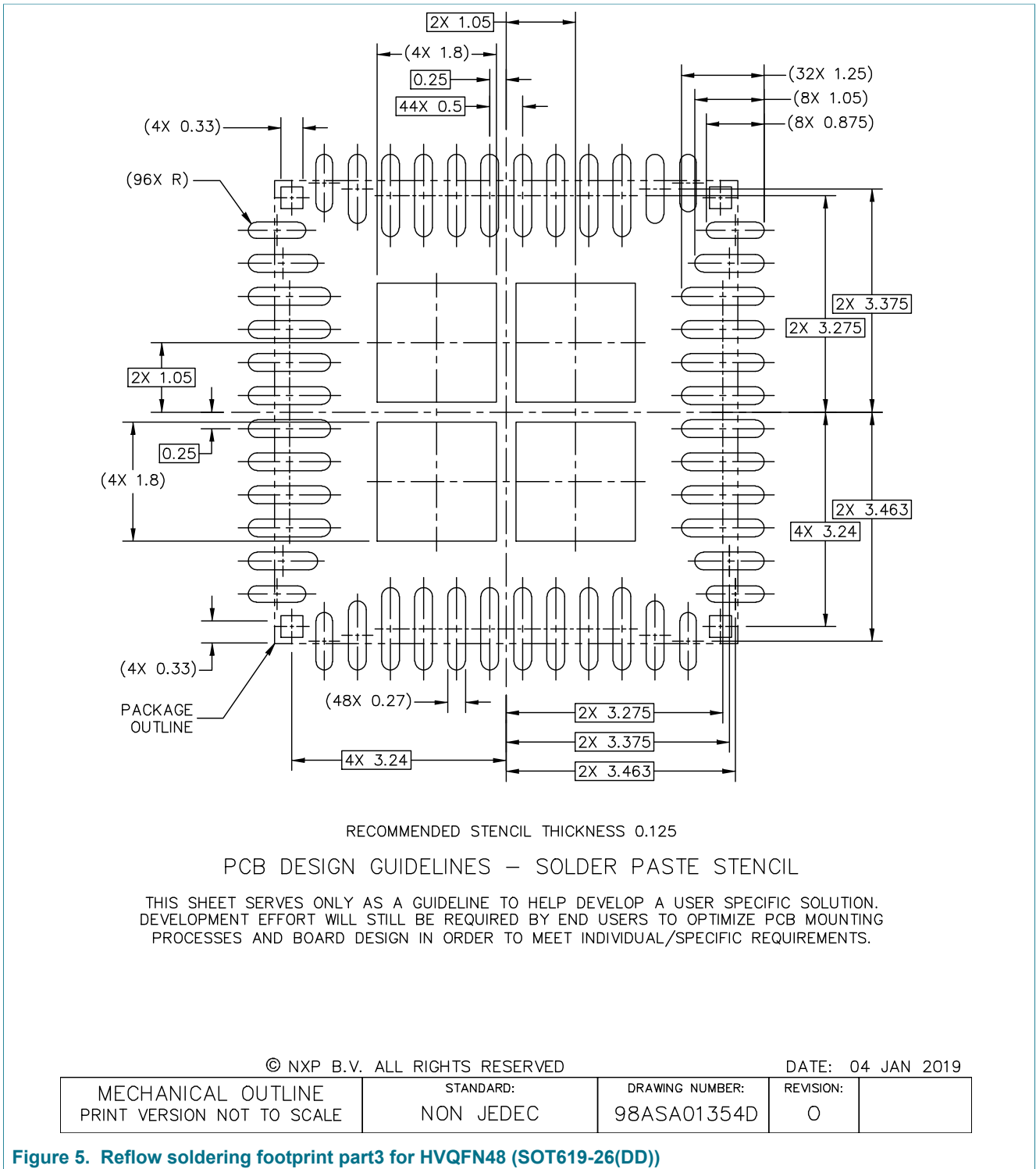


Figure 5. Reflow soldering footprint part3 for HVQFN48 (SOT619-26(DD))

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NOTES:

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN ONE CONFIGURATION MAY VARY.
- 4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
- 5. MIN. METAL GAP SHOULD BE 0.25 MM.
- 6. ANCHORING PADS.

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Figure 6. Package outline note HVQFN48 (SOT619-26(DD))

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## 4 Legal information

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